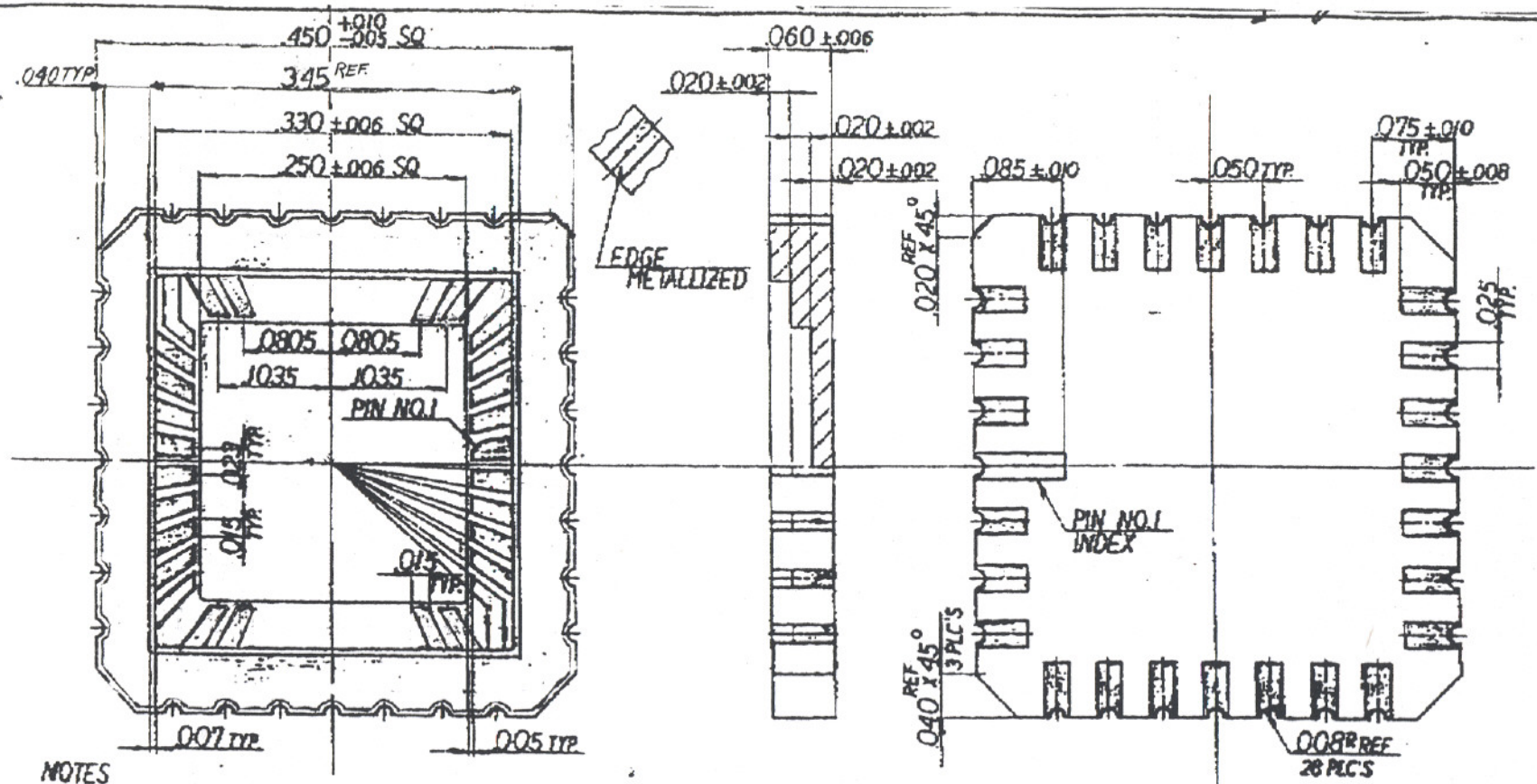

NOTES

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN THICKNESS OVER NICKEL PLATED.
2. SEAL RING FLATNESS .003
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUND TO A LEAD
4. LEAD TO LEAD LEAKAGE MUST NOT 5 NANO AMPS AT 100VD.C
5. LEAD RESISTANSE : 0.5Ω MIN.

MODIFICATIONS								
					NAME 28 LEAD CHIP CARRIER	TOLERANCES: UNLESS OTHERWISE SPECIFIED ±1% NLT ±.005	DRAWN	CHECKED
					SCALE 10/1 MATERIAL KYOCERA A-440		APPROVED	DATE 80-12-11
	CHANGE	DATE	DRAWN	CHECKED	APPROVED	KYOTO CERAMIC CO., LTD. KYOTO JAPAN	DWG. # PB-02740	